

# Alpha & Omega Semiconductor Product Reliability Report

## AOZ8S305BLS-04, rev A

**Plastic Encapsulated Device** 

**ALPHA & OMEGA Semiconductor, Inc** 

www.aosmd.com

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This AOS product reliability report summarizes the qualification result for AOZ8S305BLS-04. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOZ8S305BLS-04 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

| Test Item                | Test Condition                                       | Time Point                | Total<br>Sample<br>Size | Number<br>of<br>Failures | Reference<br>Standard |
|--------------------------|--|---------------------------|-------------------------|--------------------------|-----------------------|
| HTRB                     | Temp = 150°C,<br>Vdd=100% of VRWMmax                 | 168 / 500 /<br>1000 hours | 231 pcs                 | 0                        | JESD22-A108           |
| Precondition<br>(Note A) | 168hr 85°C / 85%RH +<br>3 cycle reflow@260°C         | -                         | 924 pcs                 | 0                        | JESD22-A113           |
| HAST                     | 130°C , 85%RH,<br>33.3 psia,<br>Vdd = 80% of VRWMmax | 96 hours                  | 231 pcs                 | 0                        | JESD22-A110           |
| Autoclave                | 121°C , 29.7psia,<br>RH=100%                         | 96 hours                  | 231 pcs                 | 0                        | JESD22-A102           |
| Temperature<br>Cycle     |  |                           | 231 pcs                 | 0                        | JESD22-A104           |
| HTSL                     | Temp = 150°C   | 1000 hours                | 231 pcs                 | 0                        | JESD22-A103           |

### I. Reliability Stress Test Summary and Results

**Note:** The reliability data presents total of available generic data up to the published date. Note A: MSL (Moisture Sensitivity Level) 1 based on J-STD-020

#### II. Reliability Evaluation

#### FIT rate (per billion): 15.26 MTTF = 7480 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

Failure Rate =  $Chi^2 x 10^9 / [2 (N) (H) (Af)] = 15.26$ MTTF =  $10^9 / FIT = 7480$  years

 $Chi^2$  = Chi Squared Distribution, determined by the number of failures and confidence interval N = Total Number of units from burn-in tests

**H** = Duration of burn-in testing

**Af** = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse =  $55^{\circ}C$ ) Acceleration Factor [**Af**] = **Exp** [Ea / k (1/Tj u - 1/Tj s)]

| Acceleration Factor ratio list: |    |          |          |          |           |           |           |           |  |  |  |
|---------------------------------|----|----------|----------|----------|-----------|-----------|-----------|-----------|--|--|--|
|                                 |    | 55 deg C | 70 deg C | 85 deg C | 100 deg C | 115 deg C | 130 deg C | 150 deg C |  |  |  |
|                                 | Af | 259      | 87       | 32       | 13        | 5.64      | 2.59      | 1         |  |  |  |

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

**Tj u** =The use junction temperature in degree (Kelvin), K = C+273.16

 $\mathbf{k}$  = Boltzmann's constant, 8.617164 X 10<sup>-5</sup> eV / K